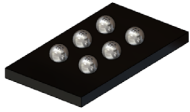


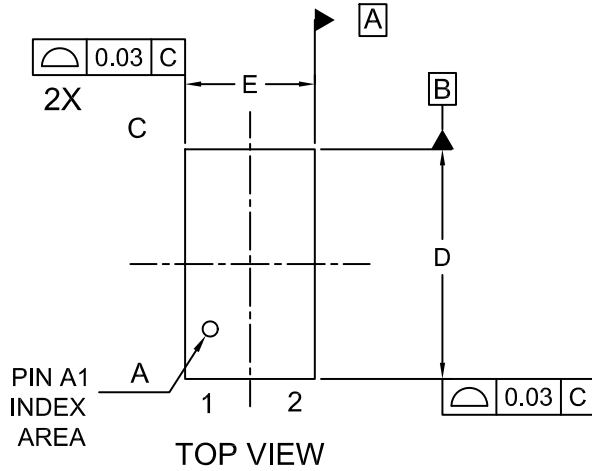
# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

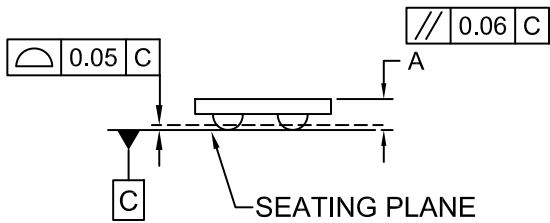
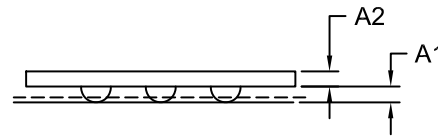


WLCSP6 2.3x1.3x0.35  
CASE 567RE  
ISSUE A

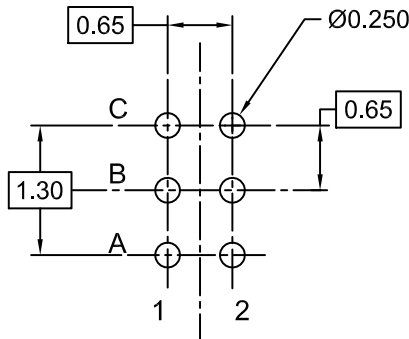
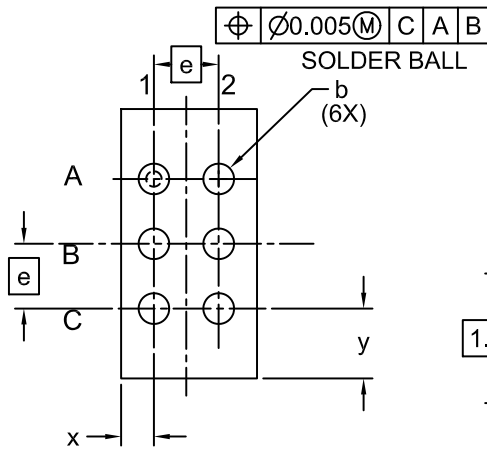
DATE 01 OCT 2021



- NOTES:
- A. NO JEDEC REGISTRATION APPLIES.
  - B. DIMENSIONS ARE IN MILLIMETERS.
  - C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 2009.
  - D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	0.35
A1	0.14	0.16	0.18
A2	0.13	0.15	0.17
b	0.27	0.30	0.33
D	1.25	1.30	1.35
E	2.25	2.30	2.35
e	0.65 BSC		
x	0.30	0.32	0.34
y	0.68	0.70	0.72



\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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